

Revision History

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
1	First Edition	Jul.29,2013	Y.Takahashi	T.Nitoube	M.Konno

[PART NUMBER LIST]

Nominal Frequency (MHz)	KYOCERA Part Number	ESR (Ω)	Nominal Frequency Code
9.84375	CX3225CA09843D0HSSTT	500	9843
10	CX3225CA10000D0HSSTT	500	10000
12	CX3225CA12000D0HSSCC	300	12000
13.56	CX3225CA13560D0HSSCC	300	13560
16	CX3225CA16000D0HSSCC	100	16000
20	CX3225CA20000D0HSSCC	100	20000
24	CX3225CA24000D0HSSCC	100	24000
25	CX3225CA25000D0HSSCC	100	25000
26	CX3225CA26000D0HSSCC	100	26000
27	CX3225CA27000D0HSSCC	100	27000
28.63636	CX3225CA28636D0HSSCC	100	28636
30	CX3225CA30000D0HSSCC	100	30000
32	CX3225CA32000D0HSSCC	100	32000
40	CX3225CA40000D0HSSCC	100	40000

1. APPLICATION

This specification sheet is applied to quartz crystal "CX3225GB"

2. KYOCERA PART NUMBER

Refer to K1101-13751-431 3/11 KYOCERA Part Number

3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature	Topr	-40~+125	°C	
Storage Temperature Range	Tstg	-40~+150	°C	

4. CHARACTERISTICS

4-1 ELECTRICAL CHARACTERISTICS

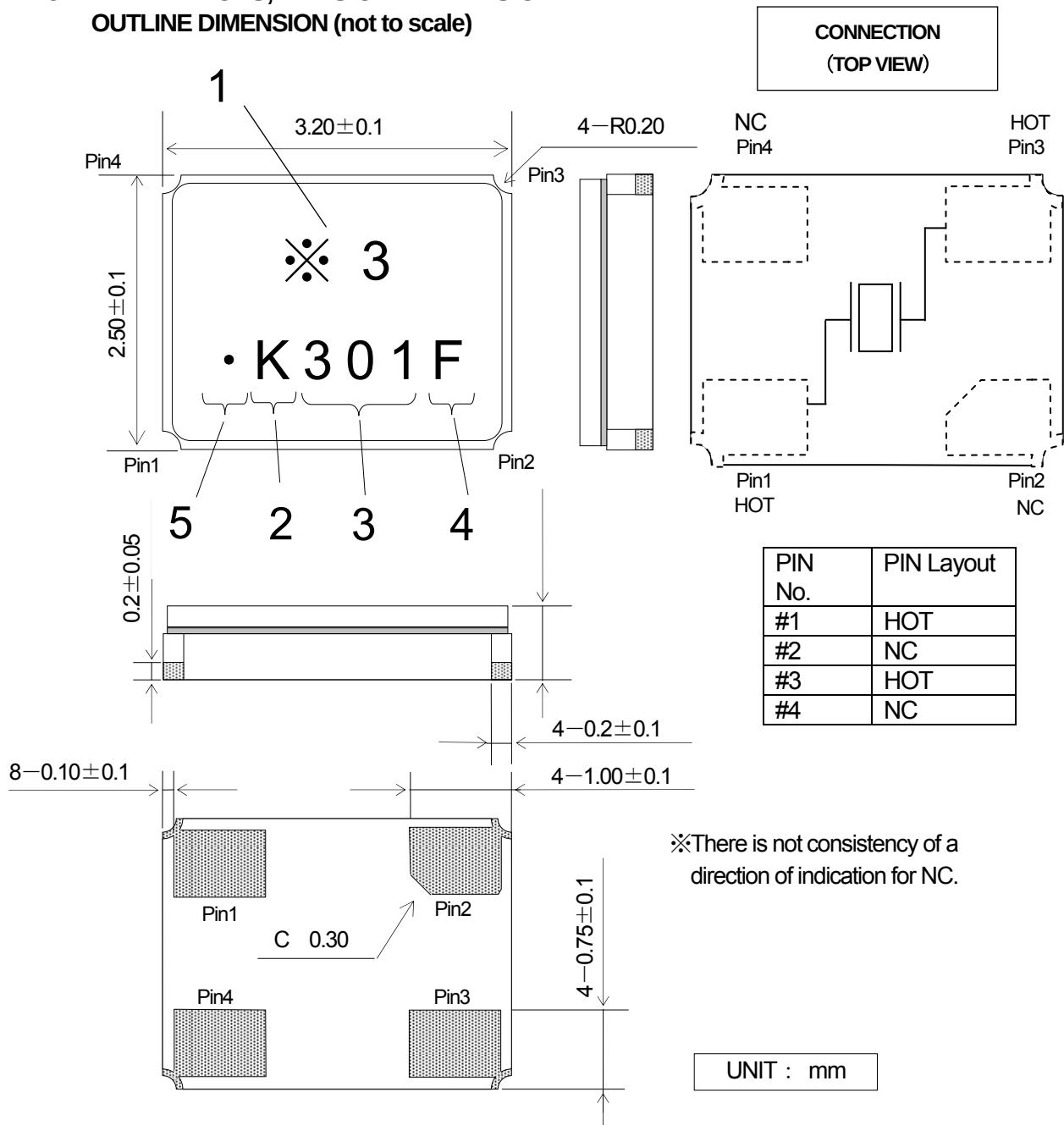
Items	Electrical Specification					Test Condition	Remarks
	SYMB.	Min.	Typ.	Max.	Unit		
Mode of Vibration		Fundamental					
Nominal Frequency	F0		※1		MHz		
Nominal Temperature	T _{NOM}		+25		°C		
Load Capacitance	CL		8.0		pF		
Frequency Tolerance	df/F	-20.0		+20.0	PPM	+25±3°C	
Frequency Temperature Characteristics	df/F	-50.0		+50.0		-40~+125°C	
Frequency Aging Rate		-5.0		+5.0		1 year	+25±3°C
Equivalent Series Resistance	ESR			※2	Ω		
Drive Level	Pd	0.01		200	μW		
Insulation Resistance	IR	500			MΩ	100V(DC)	

※1 Refer to K1101-13751-431 3/11 Nominal Frequency

※2 Refer to K1101-13751-431 3/11 ESR

5. APPEARANCES, PHYSICAL DIMENSION

OUTLINE DIMENSION (not to scale)



MARKING

1 Nominal Frequency

Move the number of maximum indication beams of the frequency to five digits, and omit less than kHz.

2 Identification

3 Date Code

Year...LAST 1 DIGIT of YEAR AND WEEK

(Ex) Jan. 1, 2013 → 301

4 Manufacturing Location

F...KYOCERA Crystal Device Philippines, Inc

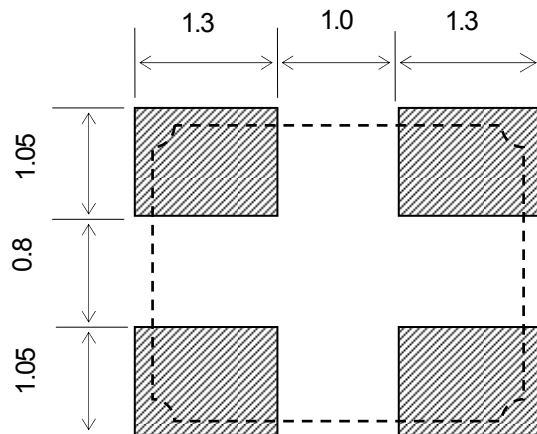
5 3 point glue mark

~11MHz Dot mark

11MHz~ No Dot mark

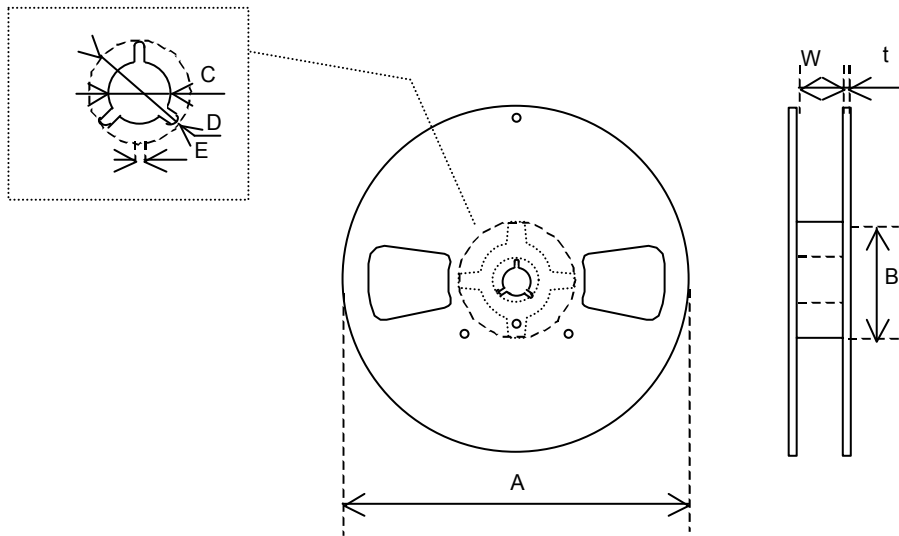
※3 Refer to K1101-13751-431 3/11 Nominal Frequency Code

The font of marking is reference.

6. RECOMMENDED LAND PATTERN (not to scale)

UNIT : mm

7-5.Reel specifications



(Nonconductor type Reel)

In the case of $\Phi 180$ Reel (3000 pcs max)

	A	B	C	D
Dimension	$\phi 180 +0/-1.5$	$\phi 60 +1/-0$	$\phi 13 \pm 0.2$	$\phi 21 \pm 0.8$
Symbol	E	W	t	
Dimension	2.0 ± 0.5	9 ± 1	2.0 ± 0.5	

(Unit : mm)

8.Environmental requirements

After following test, frequency shall not change more than $\pm 10 \times 10^{-6}$

And CI, $\pm 20\%$ or 5Ω of large value.

8.1 Resistance to Shock

Test condition

Natural dropped from height 100cm onto hard wood board in 3 times

8.2 Resistance to Vibration

Test condition

frequency : 10—55 —10 Hz
Amplitude : 1.5mm
Cycle time : 15 minutes
Direction : X,Y,Z (3direction),2 h each.

8.3 Resistance to Heat

Test condition

The quartz crystal unit shall be stored at a temperature of $+150 \pm 2^\circ\text{C}$ for 500 h.

Then it shall be subjected to standard atmospheric conditions for 1 h ,after which measurement shall be made.

8.4 Resistance to Cold

Test condition

The quartz crystal unit shall be stored at a temperature of $-40 \pm 2^\circ\text{C}$ for 500 h.

Then it shall be subjected to standard atmospheric conditions for 1 h ,after which measurement shall be made.

8.5 Thermal Shock

Test condition

The quartz crystal unit shall be subjected to 500 successive change of temperature cycles , each as shown in table below, Then it shall be subjected to standard atmospheric conditions for 1h, after which measurements shall be made.

Cycle : $-40 \pm 2^\circ\text{C}$ (30min.) to $25 \pm 2^\circ\text{C}$ (5min.)
to $+150 \pm 2^\circ\text{C}$ (30min.) to $25 \pm 2^\circ\text{C}$ (5min.)

8.6 Resistance to Moisture

Test condition

The quartz crystal unit shall be stored at a temperature of $60 \pm 2^\circ\text{C}$ with relative humidity of 90% to 95% for 500 h. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurements shall be made

8.7 Soldering condition

1.) Material of solder

Kind ... lead free solder paste

Melting point ... $+220 \pm 5^\circ\text{C}$

2.) Reflow temp.profile

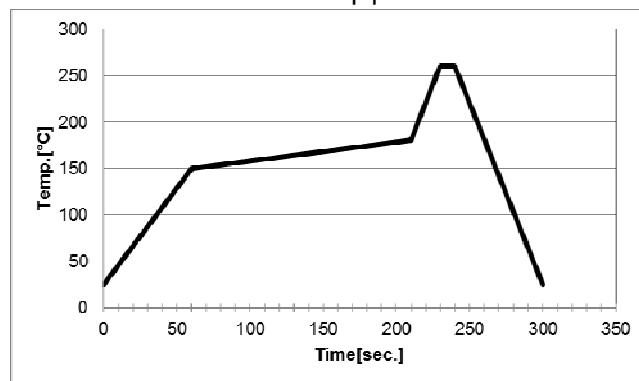
	Temp [$^\circ\text{C}$]	Time[sec]
Preheating	+150 to +180	150 (typ.)
Peak	$+260 \pm 5$	10 (max.)
Total	—	300 (max.)

Frequency shift : $\pm 2\text{ppm}$

3.) Hand Soldering $+350^\circ\text{C}$ 3 sec MAX

4.) Reflow Times 2 times

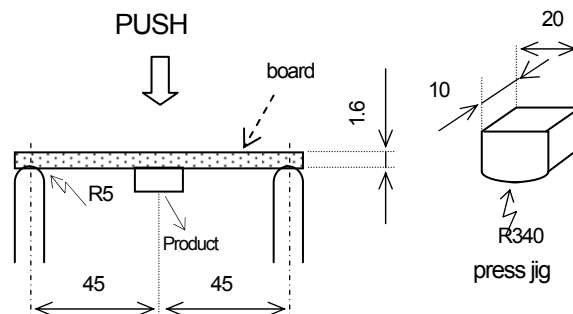
Reflow temp.profile



8.8 Intensity for bending in circuit board

Solder this product in center of the circuit board of $40\text{mm} \times 100\text{mm}$, and add the deflection of 3mm as the bottom figure.

Test board : $t = 1.6\text{mm}$



UNIT : mm

9. Cautions for use

(1) Automatic mounting machine use

Please use after affirmation that select the mounting machine model with a shock small if possible in the case of use of an automatic mounting machine, and it does not have breakage. There is a risk of a quartz crystal unit breakage occurring and not functioning normally by too much shock etc..

(2) Conformity of a circuit

In case of use of an oscillation circuit, please insert in a quartz crystal unit in series resistance 20 times as many as the standard value of equivalent in-series resistance, and confirm oscillating. Please remove resistance which inserted after the notes above-mentioned examination in the quartz crystal unit in series, and use it.

(3) After making the Quartz Crystal mount on a printed circuit board ,if it is required to divide the printed circuit board into another one, use it with attentive confirmation so that a warp caused by this dividing might not affect any damage. When designing a printed circuit board as well as handling the mounting As much as possible. The quartz crystal shall be passed through the reflow furnace. Then it shall be subjected to standard atmospheric conditions, after which cleaning shall be made.

10. Storage conditions

Storage at prolonged high temperature or low temperature and the storage by high humidity cause degradation of frequency accuracy, and degradation of soldering nature. Storage is performed at the temperature of 18-30 degrees C, and the humidity of 20-70 Percent in the state of packing, and a term is 6 months.

11. Manufacturing location

KYOCERA Crystal Device Philippines, Inc.

12. Quality Assurance

Kyocera Crystal Device Quality Assurance Division

13. Quality guarantee

When the failure by the responsibility of our company occurs clearly after delivery within 1 year, a substitute article etc. is appropriated gratuitously and this is guaranteed. However, when passing 1 year after delivery, there is a case where I am allowed to consider as onerous repair after both consultation.

14. Others

When any questions and opinions are in the written matter of these delivery specifications, I will ask connection of you from the our company issue day within 45 days. In a connection no case, a written matter is consented to it and employed within a term.